rom research to industry

Multi-Gigabit Wireless Data Transfer for High Energy Physics Applications



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- Wireless readout: context and motivation, principle of integration in HEP
- Introduction to millimeter wave, focus on 60GHz
- RFIC architecture and design
- Antenna requirement, design and integration
- Feasibility tests





# **WADAPT** Collaboration

Wadapt: "Wireless Allowing Data And Power Transmission"

## • Objectives:

- Definition of the needs of data connectivity for particle-physics detectors
- Evaluation of the wireless technologies for data and power transfer
- Hardening, specific design and prototyping
- Consortium
  - **CERN**, European Organisation for Nuclear Research, Geneva, Switzerland
  - **CEA/DSM/IRFU**, Gif-sur-Yvette, France
  - **CEA/LETI**, Grenoble, France
  - University of Heidelberg, Germany
  - University of Uppsala, Sweden
  - University of Bergen, Norway
  - **Argonne National Laboratory**, Argonne, USA
  - Gangneung National University, Korea

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# **Context: large data readout**

The **inner detector** is the first part of ATLAS to see the decay products of the collisions, so it is very compact and highly sensitive. It consists of three different systems of sensors all immersed in a magnetic field parallel to the beam axis. The Inner Detector measures the direction, momentum, and charge of electrically-charged particles produced in each proton-proton collision.

The main components of the Inner Detector are: Pixel Detector, Semiconductor Tracker (SCT), and Transition Radiation Tracker (TRT).



### **Pixel Detector**

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- 80 million pixels (80 million channels). Area 1.7m<sup>2</sup>.
   15 kW power consumption
- Barrel has 1,744 modules (10cm<sup>2</sup>) with 46,080 readout channels per module
- Pixel size 50 x 400µm<sup>2</sup>. Resolution 14 x 115µm<sup>2</sup>
- Three Pixel disks (in each endcap) have 6.6 million channels
- 3 barrel layers: 1,456 modules (i.e. 67M)
- 3 disks in each end-cap: 288 modules (i.e. 13M)

### Semiconductor Tracker

- A silicon microstrip tracker consisting of 4,088 two-sided modules and over 6 million implanted readout strips (6 million channels)
- 60m<sup>2</sup> of silicon distributed over 4 cylindrical barrel layers and 18 planar endcap discs
- Readout strips every 80µm on the silicon, allowing the positions of charged particles to be recorded to an accuracy of 17µm per layer (in the direction transverse to the strips)

### Transition Radiation Tracker

- 350,000 read-out channels
- Volume 12m<sup>3</sup>
- Basic detector element: straw tube with 4mm diameter, in the centre a 0.03mm diameter goldplated tungsten wire
- 50,000 straws in Barrel, each straw 144 cm long. The ends of a straw are read out separately
- 250,000 straws in both endcaps, each straw 39 cm long
- Precision measurement of 0.17 mm (particle track to wire)
- Provides additional information on the particle type that flew through the detector, i.e. if it is an electron or pion



# **Context: massive cable plant**



Atlas radiation length



### Impact on the measurements

- Multiple scattering and nuclear interactions
- Dead-zone areas

## • Impact on the installation and the operation

- Cables and connectors are fragile
- Cable path is not so flexible
- Design constraints

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# Why Wireless ?

- Minimize material budget of cables/connectors
   Limited radiation length because of massive services in region between Barrel and Disks
- Axial readout induce important latencies
   Direct communication between layers (radial readout)
- More flexible transceiver placement

- Point-to-Multipoint links, interlayer intelligence
- Data follows event topology enabling fast triggering





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# **E.g.: Large collider readout**



Richard Brenner – Uppsala University

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# E.g.: Large collider readout



The only sub-detector currently not used for fast trigger are the tracking detectors. To maintain current trigger thresholds at HL-LHC for maximum physics output The tracking detectors (being the most granular) can make this possible.

This will however require

- Fast data transfer for short latency
- Matching with current trigger objects
- High band-width transfer of large amount of data
- Possible data reduction on detector

Richard Brenner – Uppsala University

5/(22) WADAPT June 12, 2015

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# **Proposed approach**



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## Heidelberg Univ.

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Idea by R. Brenner (Uppsala)

## Wireless readout concept

- Radial data transfer
  - → Communciation between layers
- Signal cannot penetrate layers
  - → Reuseability of frequency channels

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# **Introduction to millimeter wave**

## Definition

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**30-300GHz** carrier frequency



## MmW Rationale

- Short wavelength
  - High level of integration, compact antenna scheme
- High free path loss
  - Suitable for short range
  - High frequency reuse
- Huge available bandwidths for high data rate communication
- Natural immunity to interference



60GHz system in package with integrated antenna

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# Introduction to millimeter wave

## Millimeter wave current applications

Radio astronomy

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- Military and space
- Cellular Infrastructure, 5G small cell
- Automotive Radar
- Wireless HD
- WLAN 802.11ad
- Imaging and security
- Short range, chip to chip, contactless connectivity













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## Huge worldwide unlicensed channels



- Favorable regulations for short range device
  - Maximum transmit power : 10dBm (Europe-Japan)
  - FCC:

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US: Recent FCC

- emission limit for UWB systems: -51.3 dBm for indoor at 3m
- 40-200GHz spurious emissions: -10 dBm EIRP max at 3m
- ETSI:
  - Unwanted emissions (frequencies beyond the limit of 250 % of the necessary bandwidth) in the spurious domain: -30dBm (in operating mode ) and -47dBm (in standbye mode)





# Features of the 60GHz band

## Short (5mm) wave length

- High free space loss:
   28dB@1cm; 48dB@10cm; 68dB@1m
- 🗕 Small antenna size
  - System in package integration





60GHz patch antenna 2.5mm

- Compatible with low cost CMOS
  - Design at <Fmax/3, <90nm node</p>
  - Passives in Back End Of Line
     High quality factor >40nm node

60GHz Si SiP



### 60GHz transmit array antenna



WiHD/802.11ad 60GHz TRx, CMOS65nm



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## Features of the 60GHz band Bluetooth LE

## Is mmw low power?



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# **RFIC architectures**

## Coherent architecture



## Non coherent architecture (On/Off keying)



16

**RFIC** architectures

- Widely used today as the most efficient (range, robustness, and spectral efficiency)
- Need power hungry PLL and digital base band processor
- Signal processing latencies

**Coherent architecture** 

Performance metrics: EVM, SNR, BER, PER

## Non coherent architecture (On/Off Keying)

- Former and simple analog technology
- Very low power, almost no latency
- Ideal for cable replacement at short range
- Weak sensitivity (short range) and spectral efficiency
- Sensitive to multi paths, interferers
- Performance metrics: eye diagram, jitter, BER, PER

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# 60GHz RFIC design







### 60GHz contactless connector (2011-2015)

### Technology:

- 60GHz OOK transceiver in CMOS SOI 65nm
- Super-regeneration receiver
- Integrated antennas

Demonstrated performances:

- HD Video streaming
- Data rate: up to 2.5Gbps
- Range: 10cm
- Power consumption: 50mW (20pJ/bit)

# E

1,9mm x 3,1mm



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# **60GHz RFIC design**



### 60GHz contactless connector (2015-2017)

### Technology:

- 60GHz ASK transceiver in CMOS 65nm
- Non coherent receiver (envelop detector)
- BGA package
- External antennas

Demonstrated performances:

- HD Video streaming (2Gbps FPGA limited)
- Data rate: up to 6Gbps
- Range: 3cm with 4dB gain antenna
- Power consumption: 35mW (<6pJ/bit)





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# 60GHz RFIC design

## **Technical features (from datasheet)**

- 60GHz V-Band transceiver for short range contactless connectivity **up to 6Gb/s**
- Compact solution integrating full RF transceiver operating in half-duplex mode with ASK modulation
- SLVS serial IO to host processor supporting 1Mb/s up to 6Gb/s with MIPI m-phy compatibility
- 60GHz TX/RX single-ended 50Ω RF ports for antenna on PCB
- Supply voltage : Dual 1.8V and 1.45V *or* single 1.8V
- RFIC control through I2C or asynchronous control pin for TX/RX mode
- Very Low power consumption: 40mW in transmit mode, 25mW in receive mode @ 5Gbps
- Dedicated RF Wake-Up idle mode with 10μW average battery consumption
- 1uW in off mode
- Package:
   VFBGA 2.2mm x 2.2mm x 1.0mm, 25 balls, F5x5, 0.4mm pitch





# **60GHz RFIC design (Heidelberg)**

# 60GHz transceiver design ongoing, dedicated to wireless readout

- Specifications in line with the HEP applications
- Technology and architecture chosen from indepth studies
  - SiGe HBT BiCMOS technology
- Comprehensive simulations on the RF blocks over PVT, mismatchs and coupling effects
- Strong attention paid to robustness and reliability
- Chip under development, timeline through 2019

Specifications	Value
Frequency band	57-66 GHz
Bandwidth	9 GHz
Data Rate	4.5 Gbps
Modulation	OOK
Minimum sensitivity S <sub>rx(min)</sub>	- 49 dBm
Bit Error Rate (BER)	10-12
Target Power consumption	250 - 150 mW
Transmission Range	20 cm (1m)



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# **RFIC design: perspectives**

## Towards 20-40Gbps, challenging the optical links

Challenges: limited range, gain, emitted power



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### Non-coherent architecture <75ps total jitter



### Coherent architecture

BER<1e-5 before decoding

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## On High Resistivity Silicon (SOI HR) antenna

- 🗕 5dB antenna gain
- 20% bandwidth

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Sensitive to wire bonding

## System in Package with antennas

- Transceiver flip-chipped close to the antennas
- Ceramic, silicon or organic interposer
- 2D or 3D interconnections
- 🗕 5-8dB gain









Interposer (bottom)



HR SOI 65nm OOK TRX 1,9\*3,1mm<sup>2</sup>





Si 6.5\*6.5mm<sup>2</sup>







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# Antenna design

## In-Package coupled antenna and focusing lens:

- Transmit array quasi-optical lens
- No mmW interconnection; +15 dB antenna gain improvement; fixed beam
- At 2Gbps: from 6cm range to 190cm range using an external lens
- Chip size: 2x3.3 mm<sup>2</sup>; package 7x7 mm<sup>2</sup>; lens 25x25 mm<sup>2</sup>





## In-Package coupled antenna and dielectric lens:

- Polyimide dielectric lens
- +8 dB antenna gain improvement
- At 2Gbps: from 6cm range to 40cm range using an external lens
- Chip size: 2x3.3 mm<sup>2</sup>; package 7x7 mm<sup>2</sup>; lens  $\emptyset$  10 mm



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## Phased array antenna with beamforming capability

- Require controllable phase shifters to steer the beam
- Single beam or multi-beams









### RF Beamforming approaches

### Fixed beam antenna array



Number of antennas



### Compact monochip TRX and phase shifters





max array factor (dB) routing loss (dB)total gain (dB)

### Satellite phase shifters





max array factor (dB) routing loss (dB)total gain (dB)

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### Beamforming with satellite phase shifter (2015)

- 2\*4 antenna array, 17dBi gain, 36dBm EIRP
- {PA, LNA, phase shifter} circuit in BICMOS55nm
  - Compensation of the power splitter and phase shifter losses
  - Vector modulator phase shifter

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3D multi-layer organic module (LCP), 20\*20mm<sup>2</sup>



LCP interposer module layout





### PA, LNA, phase shifter IC

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# **Proposed approach**

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# Wireless readout concept

- Radial data transfer
  - → Communciation between layers
- Signal cannot penetrate layers
  - → Reuseability of frequency channels

# <u>Ceatech</u> Feasibility studies, Heidelberg Univ.

## Tests in Heidelberg: line of sight transmission

### Setup in the lab

Distance: 22 cm Horn antennas from Kapton und aluminium







### 1.76 Gbps eye diagram



# Data transmission studies

- 60 GHz Tx/Rx byHittite HMC 6000/6001
  - Bandwidth: 1.8 GHz
- Setup: Bit error rate test
  - Data rate: 1.76 Gbps
  - Minimum Shift Keying  $BER < 10^{-14}$
- HD-SDI-Video transmission



PRBS 8b/10b

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- 60GHz TRX package on test board
- 9dB horn antennas
- 3cm range
- Oscilloscope eye and jitter analysis







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## Emitted wave form (60GHz)







## Receiver eye diagram (5Gbps)

- 400mV peak-peak differential
- 35ps 20-80% fall/rise time

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## Cable replacement compatibility (USB, M-PHY)

#### Budget

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#### Jitter budget @5Gbps for BER = 10e-12

		Random Jitter (ps)	Deterministic Jitter (ps)	Total Jitter (ps)
n	nipi jitter budget	Rj	Dj	Tj (ps)
	Тx	2,42	30,00	64,04
	Media	2,13	45,00	74,96
Ì	Rx	2,42	40,00	74,04
	Total	4,03	115,00	171,71
				200 max

### M-PHY standard: 75ps total jitter allowed for cable

 $T_i = D_i + 14.07 R_i$ 

### Example of measurement @ 5Gbps

Description	Mean	Std Dev	Max	Min
TIE1, Ch1	-1.1483fs	6.5838ps	19.456ps	-20.614ps
Current Acquisition	2.8881fs	6.6011ps	17.545ps	-19.785ps
Height1, Ch1	150.47mV	2.6951mV	155.04mV	146.04mV
Current Acquisition	149.81mV	V0000.0	149.81mV	149.81mV
TJ@BER1, Ch1	45.070ps	1.3558ps	47.132ps	43.128ps
Current Acquisition	46.657ps	0.0000s	46.657ps	46.657ps
RJ-δδ1, Ch1	1.4268ps	71.681fs	1.5120ps	1.3044ps
Current Acquisition	1.5075ps	0.0000s	1.5075ps	1.5075ps
DJ-δδ1, Ch1	25.094ps	641.34fs	26.207ps	24.165ps
Current Acquisition	25.552ps	0.0000s	25.552ps	25.552ps
Width@BER1, Ch1	154.93ps	1.3558ps	156.87ps	152.87ps
Current Acquisition	153.34ps	0.0000s	153.34ps	153.34ps



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## Cable replacement compatibility (USB, M-PHY)

Example of measured jitter @5Gbps with test boards



9dB horn antenna – 3dB interconnection loss



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## Cable replacement compatibility USB3 Jitter tolerance test



	spec	(DER	=	16
<del>~</del>	BER	1e-10		

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Frequency	Jitter (UI)		Jitter (ps)		
(Hz)	BER=10 <sup>-12</sup>	BER=10 <sup>-10</sup>	BER=10 <sup>-12</sup>	BER=10 <sup>-10</sup>	
$5 \times 10^{5}$	2	2.265	400	453	
$1 \times 10^{6}$	1	1.132	200	226.4	
$2x10^{6}$	0.5	0.566	100	113.2	
$4.9 \times 10^{6}$	0.205	0.232	41	46.4	
5x10 <sup>7</sup>	0.205	0.232	41	46.4	



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## Interfacing with FPGAs

Error free transmission of 8b/10b video stream at 2Gbps during a full day







## Non-coherent RFIC delay measurement: test bed

2. 1.85mm coax cable

### Comparison of delays from wired/wireless paths



## Non-coherent RFIC delay measurement: test bed





## Non-coherent RFIC delay measurement: methodology

- Measurement of relative delays in coaxial cables
- Evaluation of delays in PCB µstrip lines and connectors
- Comparison of delays between the 3 paths:

Path 1: direct transmission with 2 coaxial cables (ref. delay)
Path 2: signal experiencing emitter and receiver boards delays
+ 60GHz transmission in 1.85mm coaxial cable
Path 3: signal experiencing emitter and receiver boards delays
+ 60GHz over the air transmission (2cm range)



Wireless path

Reference wired path





# Non-coherent RFIC delay measurement: results and evaluation of delays

~400ps delay in RFIC ~280ps delay in µstrip lines ~2.7ns in 60cm 1.85mm cables @60GHz ~70ps over the air

	Eval.	Path 2 – Path 1 1 coax cable	Path 2 – Path 1 2 coax cables	Path 3 – Path 1 Over the air
τ1 (x2)	202	х	х	х
τ2 (x2)	?	388	401	394
τ3 (x2)	77	х	x	x
τ4	2730	х		
τ5	5340		x	
τ6	67			x
τ7	500			х
Total		4.09ns	6.70ns	1.98ns
Measured		4.09ns	6.70ns	1.98ns

Evaluation for the three configurations

De-embedding of transceiver delay: ~800ps for <u>both</u> emitter and receiver

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## Interfacing with plastic waveguide Extension of the range to few meters



Propagation Distance (m)

8

Path Loss (dB) comparison

Path loss comparison (in dB) for free-space propagation at 60 GHz and waveguides with attenuation constants in the range of 1 to 5 dB/m

12

16

20

"A 12 Gb/s 64QAM and OFDM Compatible Millimeter-Wave Communication Link Using a Novel Plastic Waveguide Design" F. Voineau et. al. RWS 2018



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# <u>Ceatech</u> Feasibility studies, Heidelberg Univ.

## Tests in Heidelberg: intra layer signal confinement

# Transmission through detector modules





# <u>Ceatech</u> Feasibility studies, Heidelberg Univ.

## Tests in Heidelberg: intra layer signal confinement



## Transmission: SCT Barrel Module

- Transmission loss  $I_{loss} \ge 55 \text{ dB}$
- 60 GHz signals are fully reflected
- Diffraction leads to transmission near edges

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## Ray tracing simulation: crosstalk mitigation

Approach:

- Directive horn antenna (12-17dBi gain), polarization diversity
- Graphite foam absorbing material (loss: 15-20dB transmission, 10dB reflection)









Graphite foam cover



Example for high directivity: Aluminized Kapton horn antennas ~ 12-17 dBi

# Crosstalk studies with reflections

- Under test:
   Directive antennas
   Linear polarisation
   Absorbing foam

•  $S/N = \frac{Signal Tx1_{@Rx1}}{Signal Tx2_{@Rx1}}$ 





Distance between layers: 10 cm Reference: without directive antennas and foam

# Crosstalk studies with reflections

- Highly **directive antenans** increase S/N significantly
- Orthogonal linear polarisation: S/N > 20 dB
- Foam on layers can additionaly reduce crosstalk
- 5 cm pitch between channels is possible





# **Feasibility studies**

Crosstalk: Evaluation of the required Channel/Interferer power ratio for OOK modulation





## **Coexistence** with detector



Detector performance under 60 GHz "irradiation"

- Tests done using ABC-Next Hybrid for the upgrade of ATLAS endcap detector (kindly supprted by U. Parzefall & S. Kühn, Uni Freiburg)
- Measurement: Compare noise in readout chips with and without wireless transmission

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## Coexistence with detector



Detector performance under 60 GHz "irradiation"

- No additional noise observed
- Hybrid + sensor: Temperature is dominating effect on noise per channel



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### No significant increase in noise!

## Ceatech Irradiation test, Uppsala & Heidelberg univ.

- Turku Cyclotron set-up with 17 MeV proton beam
- Target fluence: ~1e14 protons/cm2
- Sim. energy dose: 192 kGy (19 Mrad)
- Continuous performance assessment of the CMOS65nm transceiver under irradiation





## Irradiation test, Uppsala & Heidelberg univ.

## Performance during irradiation

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- No impact observed on the emitter frequency/amplitude
- Impact on the receiver low noise amplifier
- Errors obtained on the transmission
- No more errors after 3 weeks in freezer for the activity to decay

### Irradiation tests results

- Emitter: weak alteration of the performance
  - less than 1dB output power degradation
  - no influence on frequency or data rate
  - Receiver: alteration of the sensitivity
    - -4,5dB LNA gain
    - Identical envelop detector response



## New test campaign ongoing at CERN CLEAR

Neutron flux, 50Mrad cumulative dose

# Feasibility studies, conclusions

- Reliable data transmission at 60GHz using both coherent 802.11ad or non coherent transceiver
- Cable replacement with no loss in Quality of Service
- Non coherent transmission allows low latency data export
- Good intra layer signal confinement

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- Crosstalk studies. Antenna directivity and polarization diversity may be used for high density of RF links.
- Coexistence. No degradation of detector module performance observed due to 60GHz wave
- Good robustness of CMOS technology to proton and neutron radiations



- MmW allows high data rate, low power communication at short range.
- Early feasibility studies show no deadlock for their use in HEP.
- Commercial products at 60GHz should be available soon for test and can be customized for particlephysics detector.
- Early prototypes available for test.
- Future developments should challenge optical links at short range.





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# Thanks for your attention

# **Questions** ?

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